IPC ASSOCIATION ELECTRONIE	© Copyright 2005	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under bounder and Pan-American copyright conventions.			T le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribut				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				aterials and	ials and Mfg Information				
upplie	r Information						·								
ompany	name*	Company unique ID			τ	Unique ID Authority				Respo	Response Date*				
nsemi										2024-	2024-04-19				
Contact N	lame	Title - Contact			P	Phone - Contact*				Emai	Email - Contact*				
Product-	Env-Stewards		Product Enviro Compliance			1	NA				Prod	Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*	Title - Representative			P	Phone - Representative*				Emai	Email - Representative*				
Product-	Env-Stewards	Product Enviro Compliance			1	NA				Prod	Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	tive Date Version Manufacturing Site		e	Weight*	UOM	Unit Type		
		MBRS1	MBRS1100T3G REC SMB 1A 100V		V SHTKY TR		2024-04-19		CNP			101.19	mg	Each	
Ianufa	ecturing Process Inform														
	8		,		STD-020 MSL I	Rating	<u> </u>			ture Max Time at Peak Tempera			per of Reflow Cyc	eles	
	Matte Tin (Sn) - annealed	(CU Alloy	1			260		C	30	sec	onds 3			
omments															
	naximum time at peak tempera														
or more	information regarding materi	al composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Priective 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and/Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	8.19	mg	Supplier	Iron (Fe)	7439-89-6		0.0082	mg
			Supplier	Copper (Cu)	7440-50-8		8.1794	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0025	mg
Die	0.7	mg	Supplier	Silicon (Si)	7440-21-3		0.7	mg
Die Attach Solder	1.62	mg	Supplier	Silver (Ag)	7440-22-4		0.0405	mg
			A	Lead (Pb)	7439-92-1	7a	1.4985	mg
			Supplier	Tin (Sn)	7440-31-5		0.081	mg
Lead Frame	33.6	mg	Supplier	Iron (Fe)	7439-89-6		0.0336	mg
			Supplier	Copper (Cu)	7440-50-8		33.5563	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0101	mg
Mold Compound-Black	55.19	mg	Supplier	Polycondensate of 4,4'-bis(methoxymethyl)biphenyl and phenol	205830-20-2		1.3798	mg
			Supplier	Triphenylphosphine	603-35-0		0.2759	mg
			Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.2759	mg
			Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		0.2759	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5519	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		49.671	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.7595	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg